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What is "**Embedded - Microcontrollers**"?

"**Embedded - Microcontrollers**" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.
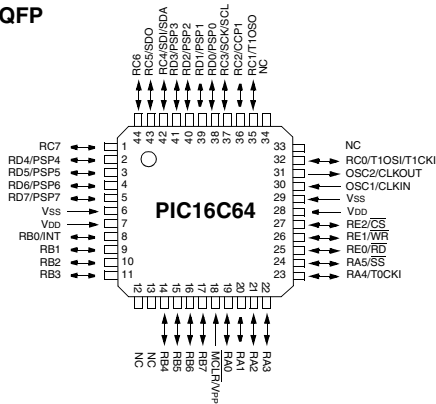
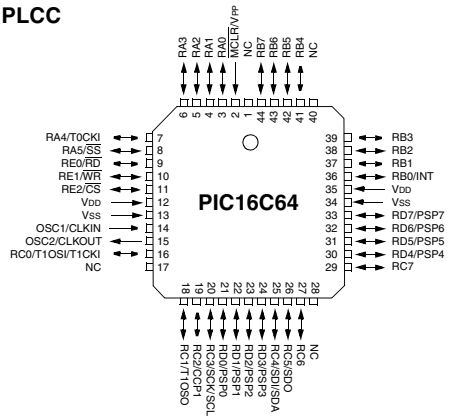### Applications of "**Embedded - Microcontrollers**"

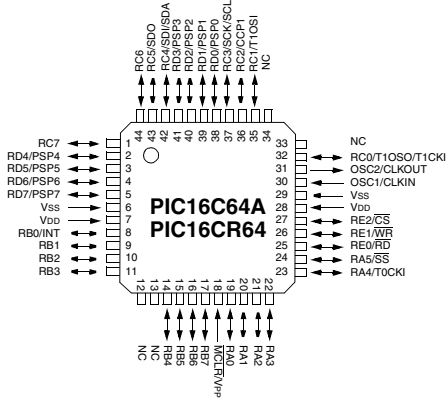| Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	14KB (8K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc67t-04i-l

Pin Diagrams (Cont.'d)

MQFP

PIC16C64

PLCC

PIC16C64

MQFP, TQFP (PIC16C64A only)

PIC16C64A
PIC16CR64

PLCC

PIC16C64A
PIC16CR64
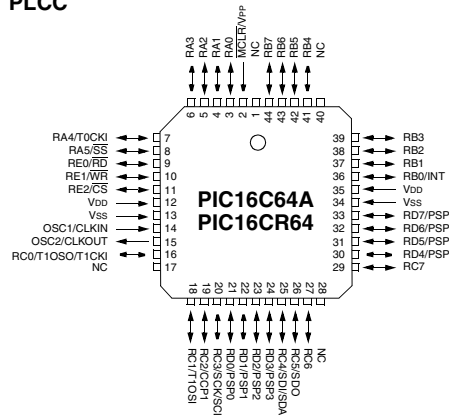
MQFP, TQFP (Not on PIC16C65)

PIC16C65
PIC16C65A
PIC16CR65
PIC16C67

PLCC

PIC16C65
PIC16C65A
PIC16CR65
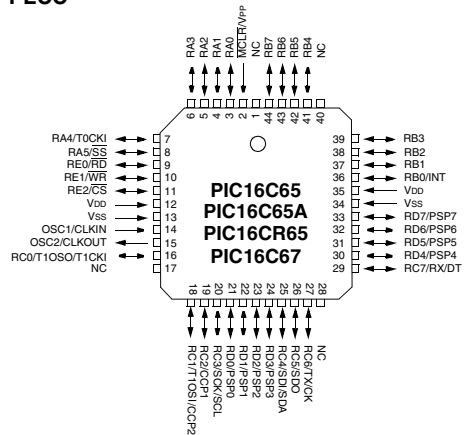**PIC16C67**
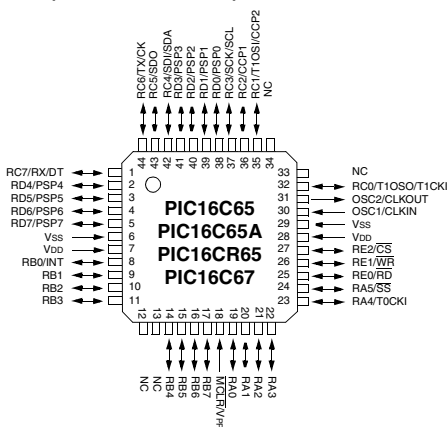
2.0 PIC16C6X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C6X Product Identification System section at the end of this data sheet. When placing orders, please use that page of the data sheet to specify the correct part number.

For the PIC16C6X family of devices, there are four device "types" as indicated in the device number:

1. **C**, as in PIC16**C**64. These devices have EPROM type memory and operate over the standard voltage range.

2. **LC**, as in PIC16**LC**64. These devices have EPROM type memory and operate over an extended voltage range.

3. **CR**, as in PIC16**CR**64. These devices have ROM program memory and operate over the standard voltage range.

4. **LCR**, as in PIC16**LCR**64. These devices have ROM program memory and operate over an extended voltage range.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the oscillator modes.

Microchip's PICSTART® Plus and PRO MATE® II programmers both support programming of the PIC16C6X.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround Production (SQTP^SM) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random, or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password, or ID number.

ROM devices do not allow serialization information in the program memory space. The user may have this information programmed in the data memory space.

For information on submitting ROM code, please contact your regional sales office.

2.5 Read Only Memory (ROM) Devices

Microchip offers masked ROM versions of several of the highest volume parts, thus giving customers a low cost option for high volume, mature products.

For information on submitting ROM code, please contact your regional sales office.

PIC16C6X

FIGURE 4-8:   PIC16C66/67 DATA MEMORY MAP

File Address

Bank 0		Bank 1		Bank 2		Bank 3	
Indirect addr.(*)	00h	Indirect addr.(*)	80h	Indirect addr.(*)	100h	Indirect addr.(*)	180h
TMR0	01h	OPTION	81h	TMR0	101h	OPTION	181h
PCL	02h	PCL	82h	PCL	102h	PCL	182h
STATUS	03h	STATUS	83h	STATUS	103h	STATUS	183h
FSR	04h	FSR	84h	FSR	104h	FSR	184h
PORTA	05h	TRISA	85h		105h		185h
PORTB	06h	TRISB	86h	PORTB	106h	TRISB	186h
PORTC	07h	TRISC	87h		107h		187h
PORTD (1)	08h	TRISD (1)	88h		108h		188h
PORTE (1)	09h	TRISE (1)	89h		109h		189h
PCLATH	0Ah	PCLATH	8Ah	PCLATH	10Ah	PCLATH	18Ah
INTCON	0Bh	INTCON	8Bh	INTCON	10Bh	INTCON	18Bh
PIR1	0Ch	PIE1	8Ch		10Ch		18Ch
PIR2	0Dh	PIE2	8Dh		10Dh		18Dh
TMR1L	0Eh	PCON	8Eh		10Eh		18Eh
TMR1H	0Fh		8Fh		10Fh		18Fh
T1CON	10h		90h		110h		190h
TMR2	11h		91h		111h		191h
T2CON	12h	PR2	92h		112h		192h
SSPBUF	13h	SSPADD	93h		113h		193h
SSPCON	14h	SSPSTAT	94h		114h		194h
CCPR1L	15h		95h		115h		195h
CCPR1H	16h		96h		116h		196h
CCP1CON	17h		97h	General Purpose Register 16 Bytes	117h	General Purpose Register 16 Bytes	197h
RCSTA	18h	TXSTA	98h		118h		198h
TXREG	19h	SPBRG	99h		119h		199h
RCREG	1Ah		9Ah		11Ah		19Ah
CCPR2L	1Bh		9Bh		11Bh		19Bh
CCPR2H	1Ch		9Ch		11Ch		19Ch
CCP2CON	1Dh		9Dh		11Dh		19Dh
	1Eh		9Eh		11Eh		19Eh
	1Fh		9Fh		11Fh		19Fh
	20h		A0h		120h		1A0h
General Purpose Register 96 Bytes		General Purpose Register 80 Bytes		General Purpose Register 80 Bytes		General Purpose Register 80 Bytes	
			EFh		16Fh		1EFh
		accesses 70h-7Fh in Bank 0	F0h	accesses 70h-7Fh in Bank 0	170h	accesses 70h-7Fh in Bank 0	1F0h
	7Fh		FFh		17Fh		1FFh

Unimplemented data memory locations, read as '0'.

*   Not a physical register.

These registers are not implemented on the PIC16C66.

Note: The upper 16 bytes of data memory in banks 1, 2, and 3 are mapped in Bank 0. This may require relocation of data memory usage in the user application code if upgrading to the PIC16C66/67.

TABLE 4-2: SPECIAL FUNCTION REGISTERS FOR THE PIC16C62/62A/R62 (Cont.'d)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets[3]
Bank 1											
80h[1]	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
81h	OPTION	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h[1]	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
83h[1]	STATUS	IRP[5]	RP1[5]	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
84h[1]	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
88h	—	Unimplemented								—	—
89h	—	Unimplemented								—	—
8Ah[1,2]	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
8Bh[1]	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	**(6)**	**(6)**	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE	00-- 0000	00-- 0000
8Dh	—	Unimplemented								—	—
8Eh	PCON	—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$[4]	---- --qq	---- --uu
8Fh	—	Unimplemented								—	—
90h	—	Unimplemented								—	—
91h	—	Unimplemented								—	—
92h	PR2	Timer2 Period Register								1111 1111	1111 1111
93h	SSPADD	Synchronous Serial Port (I²C mode) Address Register								0000 0000	0000 0000
94h	SSPSTAT	—	—	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	--00 0000	--00 0000
95h-9Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.
2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)
3: Other (non power-up) resets include external reset through $\overline{MCLR}$ and the Watchdog Timer reset.
4: The $\overline{BOR}$ bit is reserved on the PIC16C62, always maintain this bit set.
5: The IRP and RP1 bits are reserved on the PIC16C62/62A/R62, always maintain these bits clear.
6: PIE1<7:6> and PIR1<7:6> are reserved on the PIC16C62/62A/R62, always maintain these bits clear.

TABLE 4-4: **SPECIAL FUNCTION REGISTERS FOR THE PIC16C64/64A/R64**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets[3]
Bank 0											
00h[1]	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000
01h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
02h[1]	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000
03h[1]	STATUS	IRP[5]	RP1[5]	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	000q quuu
04h[1]	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	PORTA Data Latch when written: PORTA pins when read						--xx xxxx	--uu uuuu
06h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	uuuu uuuu
07h	PORTC	PORTC Data Latch when written: PORTC pins when read								xxxx xxxx	uuuu uuuu
08h	PORTD	PORTD Data Latch when written: PORTD pins when read								xxxx xxxx	uuuu uuuu
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu
0Ah[1,2]	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	---0 0000
0Bh[1]	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF	(6)	—	—	SSPIF	CCP1IF	TMR2IF	TMR1IF	00-- 0000	00-- 0000
0Dh	—	Unimplemented								—	—
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
13h	SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
15h	CCPR1L	Capture/Compare/PWM1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
18h-1Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented location read as '0'.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from either bank.
2: The upper byte of the Program Counter (PC) is not directly accessible. PCLATH is a holding register for the PC whose contents are transferred to the upper byte of the program counter. (PC<12:8>)
3: Other (non power-up) resets include external reset through $\overline{MCLR}$ and the Watchdog Timer reset.
4: The $\overline{BOR}$ bit is reserved on the PIC16C64, always maintain this bit set.
5: The IRP and RP1 bits are reserved on the PIC16C64/64A/R64, always maintain these bits clear.
6: PIE1<6> and PIR1<6> are reserved on the PIC16C64/64A/R64, always maintain these bits clear.

PIC16C6X

4.3   PCL and PCLATH

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The upper bits (PC<12:8>) are not readable, but are indirectly writable through the PCLATH register. On any reset, the upper bits of the PC will be cleared. Figure 4-24 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in the figure shows how the PC is loaded during a `CALL` or `GOTO` instruction (PCLATH<4:3> → PCH).

FIGURE 4-24:   LOADING OF PC IN DIFFERENT SITUATIONS
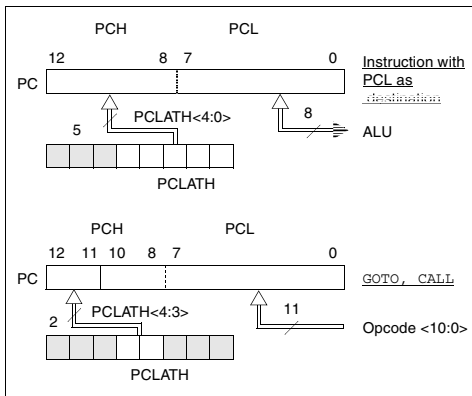
4.3.1   COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (`ADDWF PCL`). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 word block). Refer to the application note *"Implementing a Table Read"* (AN556).

4.3.2   STACK

The PIC16CXX family has an 8 deep x 13-bit wide hardware stack. The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a `CALL` instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN, RETLW` or a `RETFIE` instruction execution. PCLATH is not affected by a PUSH or a POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no status bits to indicate stack overflows or stack underflow conditions.

Note 2: There are no instructions mnemonics called PUSH or POP. These are actions that occur from the execution of the `CALL, RETURN, RETLW,` and `RETFIE` instructions, or the vectoring to an interrupt address

4.4   Program Memory Paging

Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

PIC16C6X devices are capable of addressing a continuous 8K word block of program memory. The `CALL` and `GOTO` instructions provide only 11 bits of address to allow branching within any 2K program memory page. When doing a `CALL` or `GOTO` instruction the upper two bits of the address are provided by PCLATH<4:3>. When doing a `CALL` or `GOTO` instruction, the user must ensure that the page select bits are programmed so that the desired program memory page is addressed. If a return from a `CALL` instruction (or interrupt) is executed, the entire 13-bit PC is pushed onto the stack. Therefore, manipulation of the PCLATH<4:3> bits are not required for the return instructions (which POPs the address from the stack).

Note: PIC16C6X devices with 4K or less of program memory ignore paging bit PCLATH<4>. The use of PCLATH<4> as a general purpose read/write bit is not recommended since this may affect upward compatibility with future products.

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TABLE 5-11: PORTE FUNCTIONS

Name	Bit#	Buffer Type	Function
RE0/$\overline{RD}$	bit0	ST/TTL[1]	Input/output port pin or Read control input in parallel slave port mode. $\overline{RD}$ 1 = Not a read operation 0 = Read operation. The system reads the PORTD register (if chip selected)
RE1/$\overline{WR}$	bit1	ST/TTL[1]	Input/output port pin or Write control input in parallel slave port mode. $\overline{WR}$ 1 = Not a write operation 0 = Write operation. The system writes to the PORTD register (if chip selected)
RE2/$\overline{CS}$	bit2	ST/TTL[1]	Input/output port pin or Chip select control input in parallel slave port mode. $\overline{CS}$ 1 = Device is not selected 0 = Device is selected

Legend: ST = Schmitt Trigger input, TTL = TTL input
Note 1: Buffer is a Schmitt Trigger when in I/O mode, and a TTL buffer when in Parallel Slave Port (PSP) mode.

TABLE 5-12: SUMMARY OF REGISTERS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
09h	PORTE	—	—	—	—	—	RE2	RE1	RE0	---- -xxx	---- -uuu
89h	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits			0000 -111	0000 -111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells not used by PORTE.

11.5.1.3 TRANSMISSION

When the R/$\overline{\text{W}}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{\text{W}}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{\text{ACK}}$ pulse will be sent on the ninth bit, and pin RC3/SCK/SCL is held low. The transmit data must be loaded into the SSP-BUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP (SSPCON<4>). The master must monitor the SCL pin prior to asserting another clock pulse. The slave devices may be holding off the master by stretching the clock. The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 11-26).

An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF must be cleared in software, and the SSPSTAT register is used to determine the status of the byte. Flag bit SSPIF is set on the falling edge of the ninth clock pulse.

As a slave-transmitter, the $\overline{\text{ACK}}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line was high (not $\overline{\text{ACK}}$), then the data transfer is complete. When the $\overline{\text{ACK}}$ is latched by the slave, the slave logic is reset (resets SSPSTAT register) and the slave then monitors for another occurrence of the START bit. If the SDA line was low ($\overline{\text{ACK}}$), the transmit data must be loaded into the SSPBUF register, which also loads the SSPSR register. Then pin RC3/SCK/SCL should be enabled by setting bit CKP.

FIGURE 11-26: I^{2}C WAVEFORMS FOR TRANSMISSION (7-BIT ADDRESS)
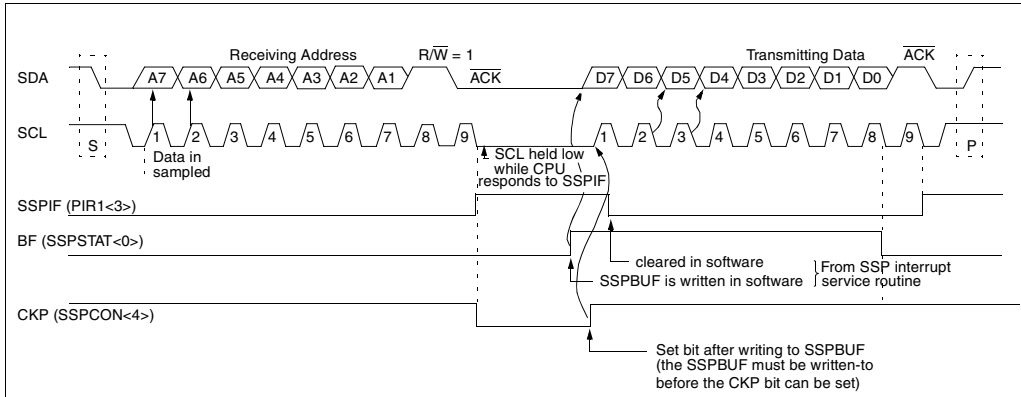
FIGURE 12-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER (ADDRESS 18h)

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D

bit7   bit0

```
R  = Readable bit
W  = Writable bit
U  = Unimplemented
     bit, read as '0'
- n = Value at POR reset
x  = unknown
```

bit 7: **SPEN**: Serial Port Enable bit
(Configures RC7/RX/DT and RC6/TX/CK pins as serial port pins when bits TRISC<7:6> are set)
1 = Serial port enabled
0 = Serial port disabled

bit 6: **RX9**: 9-bit Receive Enable bit
1 = Selects 9-bit reception
0 = Selects 8-bit reception

bit 5: **SREN**: Single Receive Enable bit

Asynchronous mode
Don't care

Synchronous mode - master
1 = Enables single receive
0 = Disables single receive
This bit is cleared after reception is complete.

Synchronous mode - slave
Unused in this mode

bit 4: **CREN**: Continuous Receive Enable bit

Asynchronous mode
1 = Enables continuous receive
0 = Disables continuous receive

Synchronous mode
1 = Enables continuous receive until enable bit CREN is cleared (CREN overrides SREN)
0 = Disables continuous receive

bit 3: **Unimplemented:** Read as '0'

bit 2: **FERR**: Framing Error bit
1 = Framing error (Can be updated by reading RCREG register and receive next valid byte)
0 = No framing error

bit 1: **OERR**: Overrun Error bit
1 = Overrun error (Can be cleared by clearing bit CREN)
0 = No overrun error

bit 0: **RX9D**: 9th bit of received data (Can be parity bit)

Steps to follow when setting up an Asynchronous Transmission:

1. Initialize the SPBRG register for the appropriate baud rate. If a high speed baud rate is desired, then set bit BRGH. (Section 12.1).
2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set transmit bit TX9.
5. Enable the transmission by setting bit TXEN, which will also set bit TXIF.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Load data to the TXREG register (starts transmission).

FIGURE 12-8: ASYNCHRONOUS MASTER TRANSMISSION
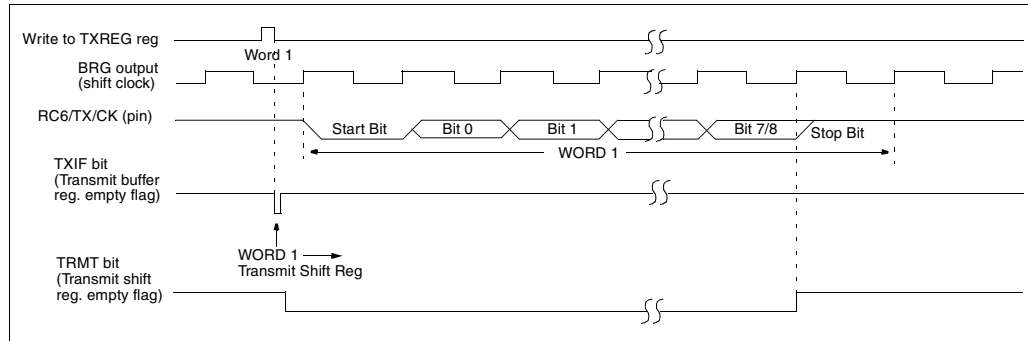
FIGURE 12-9: ASYNCHRONOUS MASTER TRANSMISSION (BACK TO BACK)

Note: This timing diagram shows two consecutive transmissions.
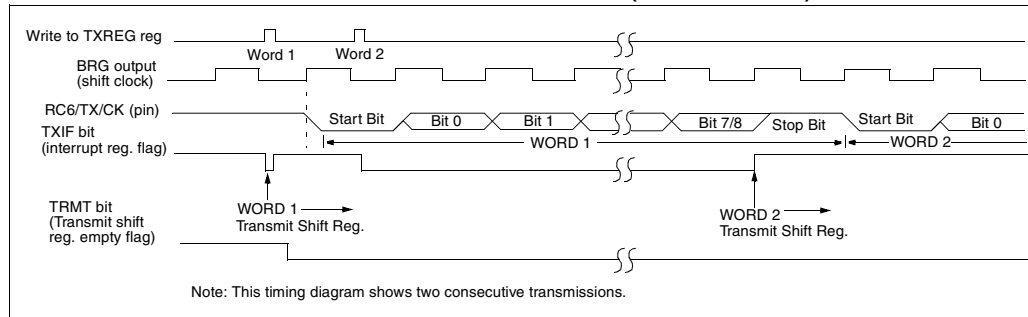
TABLE 12-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
0Ch	PIR1	PSPIF[1]	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
18h	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00x
19h	TXREG	USART Transmit Register								0000 0000	0000 0000
8Ch	PIE1	PSPIE[1]	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented locations read as '0'. Shaded cells are not used for Asynchronous Transmission.

Note 1: PSPIF and PSPIE are reserved on the PIC16C63/R63/66, always maintain these bits clear.

    2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

NOP — No Operation

NOP	No Operation
Syntax:	[*label*] NOP
Operands:	None
Operation:	No operation
Status Affected:	None

Encoding:

00	0000	0xx0	0000

Description:	No operation.
Words:	1
Cycles:	1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	No-Operation	No-Operation

Example   NOP

OPTION — Load Option Register

OPTION	Load Option Register
Syntax:	[*label*] OPTION
Operands:	None
Operation:	(W) → OPTION
Status Affected:	None

Encoding:

00	0000	0110	0010

Description:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.
Words:	1
Cycles:	1
Example	

To maintain upward compatibility with future PIC16CXX products, do not use this instruction.

RETFIE — Return from Interrupt

RETFIE	Return from Interrupt
Syntax:	[*label*] RETFIE
Operands:	None
Operation:	TOS → PC, 1 → GIE
Status Affected:	None

Encoding:

00	0000	0000	1001

Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two cycle instruction.
Words:	1
Cycles:	2

Q Cycle Activity:

	Q1	Q2	Q3	Q4
1st Cycle	Decode	No-Operation	Set the GIE bit	Pop from the Stack
2nd Cycle	No-Operation	No-Operation	No-Operation	No-Operation

Example   RETFIE

After Interrupt
        PC =   TOS
        GIE =   1

PIC16C6X

SLEEP

Syntax:	[*label*] SLEEP
Operands:	None
Operation:	00h → WDT, 0 → WDT prescaler, 1 → $\overline{TO}$, 0 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down status bit, $\overline{PD}$ is cleared. Time-out status bit, $\overline{TO}$ is set. Watchdog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See Section 13.8 for more details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No-Operation	No-Operation	Go to Sleep

Example: `SLEEP`

SUBLW   Subtract W from Literal

Syntax:	[*label*] SUBLW k
Operands:	$0 \leq k \leq 255$
Operation:	k - (W) → (W)
Status Affected:	C, DC, Z

Encoding:

11	110x	kkkk	kkkk

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example 1:   `SUBLW   0x02`

Before Instruction

W	=	1
C	=	?
Z	=	?

After Instruction

W	=	1
C	=	1; result is positive
Z	=	0

Example 2:   Before Instruction

W	=	2
C	=	?
Z	=	?

After Instruction

W	=	0
C	=	1; result is zero
Z	=	1

Example 3:   Before Instruction

W	=	3
C	=	?
Z	=	?

After Instruction

W	=	0xFF
C	=	0; result is negative
Z	=	0

Applicable Devices | 61 | 62 | 62A | R62 | 63 | R63 | 64 | 64A | R64 | 65 | 65A | R65 | 66 | 67

FIGURE 15-4: **RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING**

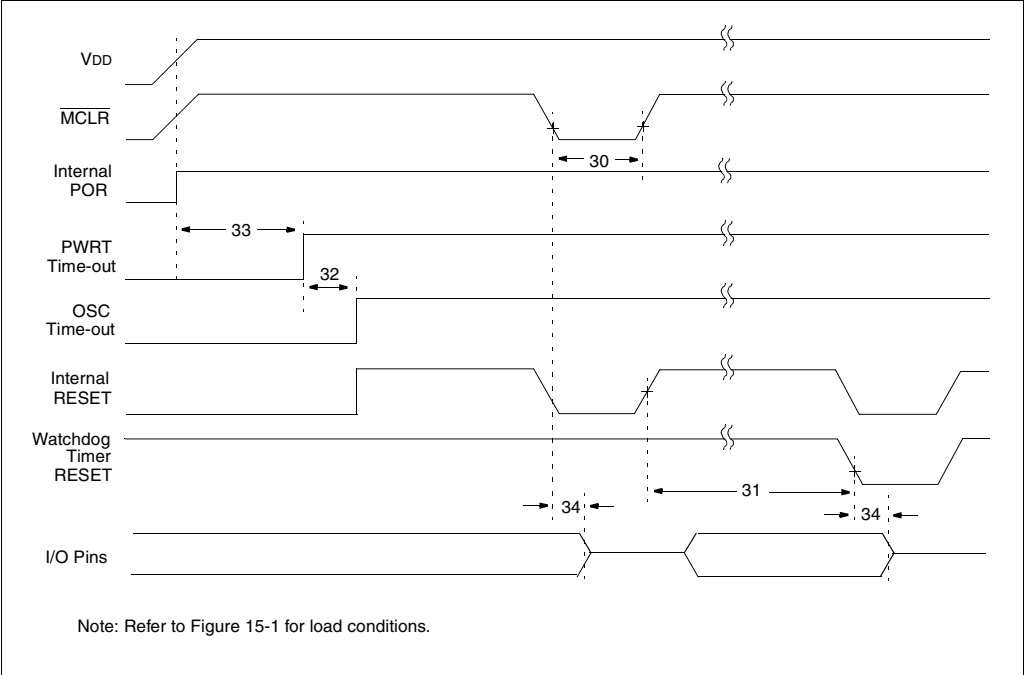Note: Refer to Figure 15-1 for load conditions.

TABLE 15-4: **RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30*	TmcL	$\overline{MCLR}$ Pulse Width (low)	200	—	—	ns	V_{DD} = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	V_{DD} = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	—	1024T_{OSC}	—		T_{OSC} = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	V_{DD} = 5V, -40°C to +125°C
34*	T$_{IOZ}$	I/O Hi-impedance from $\overline{MCLR}$ Low	—	—	100	ns	

*   These parameters are characterized but not tested.

†   Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

18.0 ELECTRICAL CHARACTERISTICS FOR PIC16C62A/R62/64A/R64

Absolute Maximum Ratings †

Ambient temperature under bias...-55°C to +125°C

Storage temperature ....-65°C to +150°C

Voltage on any pin with respect to VSS (except VDD, $\overline{MCLR}$, and RA4)...-0.3V to (VDD + 0.3V)

Voltage on VDD with respect to VSS .... -0.3V to +7.5V

Voltage on $\overline{MCLR}$ with respect to VSS (Note 2)...0V to +14V

Voltage on RA4 with respect to Vss .... 0V to +14V

Total power dissipation (Note 1)...1.0W

Maximum current out of VSS pin ....300 mA

Maximum current into VDD pin ....250 mA

Input clamp current, IIK (VI < 0 or VI > VDD)...±20 mA

Output clamp current, IOK (VO < 0 or VO > VDD) ....±20 mA

Maximum output current sunk by any I/O pin..25 mA

Maximum output current sourced by any I/O pin ....25 mA

Maximum current sunk by PORTA, PORTB, and PORTE (combined)..200 mA

Maximum current sourced by PORTA, PORTB, and PORTE (combined) ....200 mA

Maximum current sunk by PORTC and PORTD (combined) ....200 mA

Maximum current sourced by PORTC and PORTD (combined)..200 mA

Note 1: Power dissipation is calculated as follows: Pdis = VDD x {IDD - ∑ IOH} + ∑ {(VDD-VOH) x IOH} + ∑(VOl x IOL)

Note 2: Voltage spikes below VSS at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 18-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC16C62A-04 PIC16CR62-04 PIC16C64A-04 PIC16CR64-04	PIC16C62A-10 PIC16CR62-10 PIC16C64A-10 PIC16CR64-10	PIC16C62A-20 PIC16CR62-20 PIC16C64A-20 PIC16CR64-20	PIC16LC62A-04 PIC16LCR62-04 PIC16LC64A-04 PIC16LCR64-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq:4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 μA max. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq:4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 2.0 mA typ. at 5.5V IPD: 1.5 μA typ. at 4V Freq: 4 MHz max.	VDD: 2.5V to 6.0V IDD: 3.8 mA max. at 3.0V IPD: 5 μA max. at 3.0V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 5 mA max. at 5.5V IPD: 16 μA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 10 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 10 MHz max.	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 20 mA max. at 5.5V IPD: 1.5 μA typ. at 4.5V Freq: 20 MHz max.

LP	VDD: 4.0V to 6.0V
	IDD: 52.5 μA typ.
	   at 32 kHz, 4.0V
	IPD: 0.9 μA typ. at 4.0V
	Freq: 200 kHz max.
		Not recommended for use in LP mode	Not recommended for use in LP mode	VDD: 2.5V to 6.0V
				IDD: 48 μA max. at 32 kHz, 3.0V
				IPD: 5 μA max. at 3.0V
				Freq: 200 kHz max.
					VDD: 2.5V to 6.0V
					IDD: 48 μA max.
					   at 32 kHz, 3.0V
					IPD: 5 μA max. at 3.0V
					Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

18.2   DC Characteristics: PIC16LC62A/R62/64A/R64-04 (Commercial, Industrial)

DC CHARACTERISTICS							Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C $\leq$ TA $\leq$ +85°C for industrial and 0°C $\leq$ TA $\leq$ +70°C for commercial
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001	Supply Voltage	VDD	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3, 5)	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	ΔIBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

*   These parameters are characterized but not tested.

†   Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

FIGURE 18-9: SPI MODE TIMING

Note: Refer to Figure 18-1 for load conditions
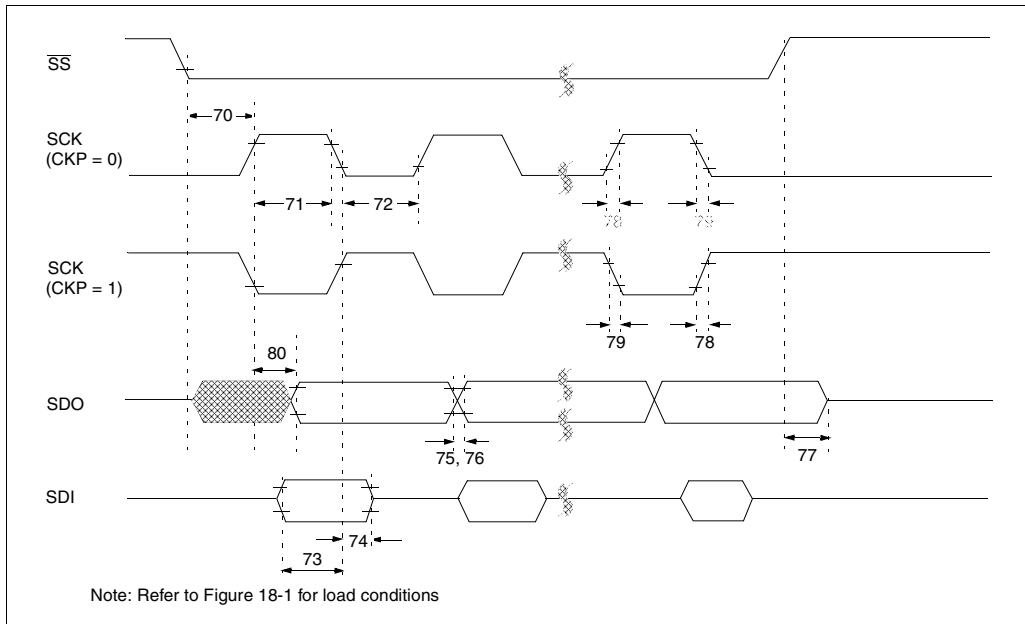
TABLE 18-8: SPI MODE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK↓ or SCK↑ input	TCY	—	—	ns	
71*	TscH	SCK input high time (slave mode)	TCY + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	50	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	50	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

*   These parameters are characterized but not tested.

†   Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 21-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)
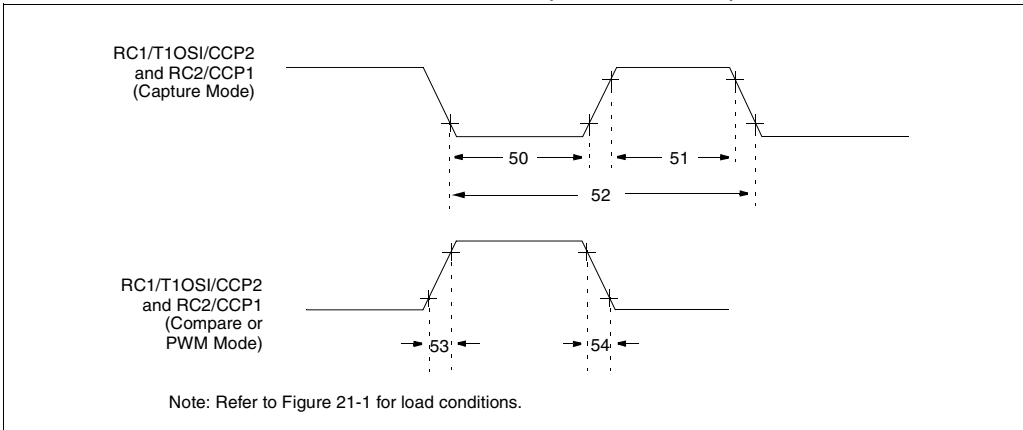
TABLE 21-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16**CR**63/R65	10	—	—	ns	
				PIC16**LCR**63/R65	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16**CR**63/R65	10	—	—	ns	
				PIC16**LCR**63/R65	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4, or 16)
53*	TccR	CCP1 and CCP2 output rise time	PIC16**CR**63/R65		—	10	25	ns	
			PIC16**LCR**63/R65		—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time	PIC16**CR**63/R65		—	10	25	ns	
			PIC16**LCR**63/R65		—	25	45	ns	

*   These parameters are characterized but not tested.

†   Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C6X

22.3   DC Characteristics: PIC16C66/67-04 (Commercial, Industrial, Extended)
PIC16C66/67-10 (Commercial, Industrial, Extended)
PIC16C66/67-20 (Commercial, Industrial, Extended)
PIC16LC66/67-04 (Commercial, Industrial)

DC CHARACTERISTICS	**Standard Operating Conditions (unless otherwise stated)**					
	Operating temperature $-40°C \le T_A \le +125°C$ for extended, $-40°C \le T_A \le +85°C$ for industrial and $0°C \le T_A \le +70°C$ for commercial					
	Operating voltage V_{DD} range as described in DC spec Section 22.1 and Section 22.2					
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
---	---	---	---	---	---	---	---
	Input Low Voltage						
	I/O ports	V_{IL}					
D030	with TTL buffer		V_{SS}	-	$0.15V_{DD}$	V	For entire V_{DD} range
D030A			V_{SS}	-	0.8V	V	$4.5V \le V_{DD} \le 5.5V$
D031	with Schmitt Trigger buffer		V_{SS}	-	$0.2V_{DD}$	V	
D032	$\overline{MCLR}$, OSC1 (in RC mode)		V_{SS}	-	$0.2V_{DD}$	V	
D033	OSC1 (in XT, HS and LP)		V_{SS}	-	$0.3V_{DD}$	V	Note1
	Input High Voltage						
	I/O ports	V_{IH}		-			
D040	with TTL buffer		2.0	-	V_{DD}	V	$4.5V \le V_{DD} \le 5.5V$
D040A			$0.25V_{DD}$ + 0.8V	-	V_{DD}	V	For entire V_{DD} range
D041	with Schmitt Trigger buffer		$0.8V_{DD}$	-	V_{DD}	V	For entire V_{DD} range
D042	$\overline{MCLR}$		$0.8V_{DD}$	-	V_{DD}	V	
D042A	OSC1 (XT, HS and LP)		$0.7V_{DD}$	-	V_{DD}	V	Note1
D043	OSC1 (in RC mode)		$0.9V_{DD}$	-	V_{DD}	V	
D070	PORTB weak pull-up current	I_{PURB}	50	250	400	µA	$V_{DD} = 5V$, $V_{PIN} = V_{SS}$
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	I_{IL}	-	-	±1	µA	$V_{SS} \le V_{PIN} \le V_{DD}$, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	µA	$V_{SS} \le V_{PIN} \le V_{DD}$
D063	OSC1		-	-	±5	µA	$V_{SS} \le V_{PIN} \le V_{DD}$, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	V_{OL}	-	-	0.6	V	$I_{OL} = 8.5$ mA, $V_{DD} = 4.5V$, -40°C to +85°C
D080A			-	-	0.6	V	$I_{OL} = 7.0$ mA, $V_{DD} = 4.5V$, -40°C to +125°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	$I_{OL} = 1.6$ mA, $V_{DD} = 4.5V$, -40°C to +85°C
D083A			-	-	0.6	V	$I_{OL} = 1.2$ mA, $V_{DD} = 4.5V$, -40°C to +125°C

*   These parameters are characterized but not tested.

†   Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67

22.5   Timing Diagrams and Specifications

FIGURE 22-2:   EXTERNAL CLOCK TIMING
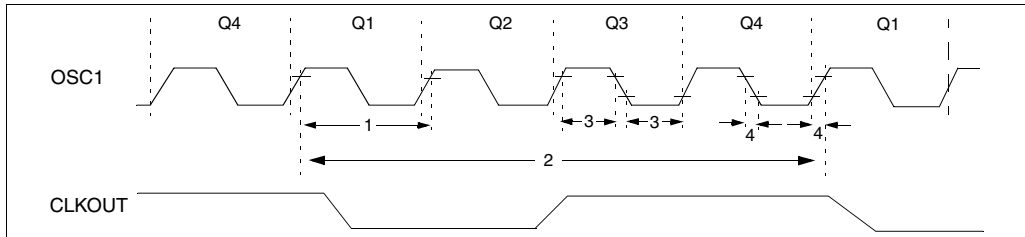
TABLE 22-2:   EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency** (Note 1)	DC	—	4	MHz	XT and RC osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	Tosc	**External CLKIN Period** (Note 1)	250	—	—	ns	XT and RC osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	TCY	DC	ns	$T_{CY} = 4/F_{OSC}$
3*	TosL, TosH	**External Clock in (OSC1) High or Low Time**	100	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.